

Product / Process Change Notification



N° 2015-026-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Change of wafer fab location and change of wafer diameter from 8 inch to 12 inch affecting product BTS50015-1TAD

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **30. June 2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: “**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”
- This PCN includes a **Product Discontinuation Notice** (JEDEC STANDARD “JESD48“) on page 4/4.

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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► Products affected:

Sales Name	SP N°	OPN	Package
BTS50015-1TAD	SP001134858	BTS500151TADATMA1	PG-TO263-7

► Detailed Change Information:

Subject: Transfer of wafer production to IFX Dresden (Germany), change of wafer diameter from 8 inch to 12 inch and minor change of the Package.

Reason: Due to continuously raising demand for Infineon automotive products we have to implement the well-known front end (FE) location Dresden as an additional wafer fab location.

Description:

	<u>Old</u>	<u>New</u>
Wafer Diameter	8 inch	12 inch
Wafer production	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies Dresden, Germany
Package	PG-TO263-7-8	PG-TO263-7-10
Datasheet	Die pad chamfered „cooling tab“ Rev. 1.1	Die pad rectangular „cooling tab“ Rev. 1.2

► Product Identification:

Old Marking: S50015D
New Marking: S50015D

► Impact of Change:

No impact on electrical performance. Quality and reliability verified by qualification.
There is no change in form, fit and function.

► Attachments:

4_cip15026A Datasheet

► Time Schedule:

- | | |
|-------------------------------|------------|
| ■ Final qualification report: | available |
| ■ First samples available: | on request |
| ■ Intended start of delivery: | 01.12.2017 |

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Refer to page 4/4:

■ Last order date of unchanged product: 01.12.2017

■ Last delivery date of unchanged product: 01.06.2018

If you have any questions, please do not hesitate to contact your local Sales office.

PRODUCT DISCONTINUATION

PD15026



referring to PCN N° 2015-026-A

■ Last order date of unchanged product:	2017-12-01
■ Last delivery date of unchanged product:	2018-06-01

DISCONTINUED				NEW (REPLACEMENT)			
Device	Ordering Code	OPN	Package	Device	Ordering Code	OPN	Package
BTS50015-1TAD	SP001134858	BTS500151TADATMA1	PG-TO263-7-8	BTS50015-1TAD	SP001699382	BTS500151TADATMA2	PG-TO263-7-10